

WIDE BAND DPDT SWITCH

DESCRIPTION

The μ PD5738T6N is a CMOS MMIC DPDT (Double Pole Double Throw) switch which is developed for mobile communications, wireless communications and another RF switching applications.

This device can operate within frequency from 0.01 to 2.5 GHz, having low insertion loss and high isolation performances. This device is housed in a 6-pin plastic TSON (Thin Small Out-line Non-leaded) (T6N) package, which allows high-density surface mounting.

FEATURES

- Supply voltage : $V_{DD} = 1.5$ to 3.6 V (2.8 V TYP.)
- Switch control voltage : $V_{cont(H)} = 1.5$ to 3.6 V (2.8 V TYP.)
: $V_{cont(L)} = -0.2$ to $+0.4$ V (0 V TYP.)
- Low insertion loss ^{Note} : $L_{ins1} = 0.5$ dB TYP. @ $f = 0.01$ to 0.05 GHz
: $L_{ins2} = 0.8$ dB TYP. @ $f = 0.05$ to 1.0 GHz
: $L_{ins3} = 1.4$ dB TYP. @ $f = 1.0$ to 2.0 GHz
: $L_{ins4} = 1.6$ dB TYP. @ $f = 2.0$ to 2.5 GHz
- High isolation ^{Note} : $ISL1 = 45$ dB TYP. @ $f = 0.01$ to 0.05 GHz
: $ISL2 = 22$ dB TYP. @ $f = 0.05$ to 1.0 GHz
: $ISL3 = 16$ dB TYP. @ $f = 1.0$ to 2.0 GHz
: $ISL4 = 15$ dB TYP. @ $f = 2.0$ to 2.5 GHz
- Handling power ^{Note} : $P_{in(1dB)} = +20$ dBm TYP. @ $f = 1.0$ GHz
: $P_{in(0.1dB)} = +15$ dBm TYP. @ $f = 1.0$ GHz
- High-density surface mounting: 6-pin plastic TSON (T6N) package ($1.5 \times 1.5 \times 0.37$ mm)
- High ESD voltage : machine-model 200 V (TYP.), human-body-model 3 kV (TYP.)

Note $T_A = 25^\circ\text{C}$, $V_{DD} = 2.8$ V, $V_{cont(H)} = 2.8$ V, $V_{cont(L)} = 0$ V

APPLICATIONS

- Mobile communications
- Wireless communications
- Another RF switching applications

ORDERING INFORMATION

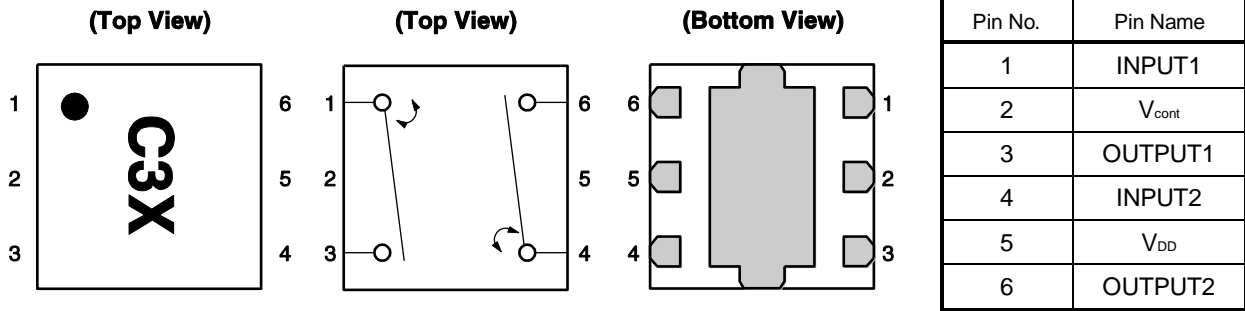
Part Number	Order Number	Package	Marking	Supplying Form
μ PD5738T6N-E2	μ PD5738T6N-E2-A	6-pin plastic TSON (T6N) (Pb-Free)	C3X	<ul style="list-style-type: none"> • Embossed tape 8 mm wide • Pin 1, 6 face the perforation side of the tape • Qty 3 kpcs/reel

Remark To order evaluation samples, please contact your nearby sales office.
Part number for sample order: μ PD5738T6N-A

Caution: Observe precautions when handling because these devices are sensitive to electrostatic discharge

The information in this document is subject to change without notice. Before using this document, please confirm that this is the latest version.

PIN CONNECTIONS AND INTERNAL BLOCK DIAGRAM



Remark Exposed pad : GND

TRUTH TABLE

V _{cont}	INPUT1-OUTPUT1, INPUT2-OUTPUT2	INPUT1-OUTPUT2, INPUT2-OUTPUT1
Low	ON	OFF
High	OFF	ON

Remark High: +2.8 V, Low: 0 V

ABSOLUTE MAXIMUM RATINGS (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Supply Voltage	V _{DD}	-0.5 to +4.6	V
Switch Control Voltage	V _{cont}	-0.5 to +4.6	V
Voltage Difference	V _{cont (H)} - V _{DD}	+0.5	V
Input Power	P _{in}	+23	dBm
Operating Ambient Temperature	T _A	-45 to +85	°C
Storage Temperature	T _{stg}	-55 to +150	°C

RECOMMENDED OPERATING RANGE (T_A = +25°C, unless otherwise specified)

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply Voltage	V _{DD}	+1.5	+2.8	+3.6	V
Switch Control Voltage (H)	V _{cont (H)}	+1.5	+2.8	+3.6	V
Switch Control Voltage (L)	V _{cont (L)}	-0.2	0	+0.4	V

Remark V_{DD} - 0.4 V ≤ V_{cont (H)} ≤ V_{DD} + 0.2 V

ELECTRICAL CHARACTERISTICS

($T_A = +25^\circ\text{C}$, $V_{DD} = 2.8\text{ V}$, $V_{\text{cont(H)}} = 2.8\text{ V}$, $V_{\text{cont(L)}} = 0\text{ V}$, $P_{\text{in}} = 0\text{ dBm}$, $Z_0 = 50\ \Omega$, DC blocking capacitors = 10 000 pF, unless otherwise specified)

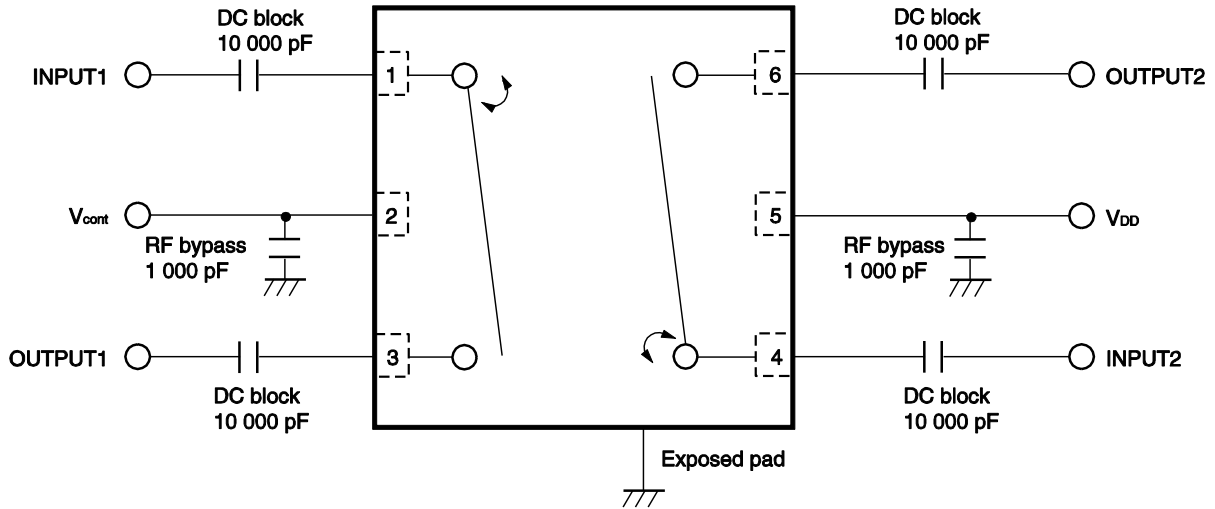
Parameter	Symbol	Test Conditions	MIN.	TYP.	MAX.	Unit
Insertion Loss 1	L _{ins1}	f = 0.01 to 0.05 GHz	–	0.5	0.9	dB
Insertion Loss 2	L _{ins2}	f = 0.05 to 1.0 GHz	–	0.8	1.2	dB
Insertion Loss 3	L _{ins3}	f = 1.0 to 2.0 GHz	–	1.4	1.8	dB
Insertion Loss 4	L _{ins4}	f = 2.0 to 2.5 GHz	–	1.6	2.0	dB
Isolation 1	ISL1	f = 0.01 to 0.05 GHz	35	45	–	dB
Isolation 2	ISL2	f = 0.05 to 1.0 GHz	18	22	–	dB
Isolation 3	ISL3	f = 1.0 to 2.0 GHz	13	16	–	dB
Isolation 4	ISL4	f = 2.0 to 2.5 GHz	12	15	–	dB
Return Loss 1	RL1	f = 0.01 to 1.0 GHz	13	18	–	dB
Return Loss 2	RL2	f = 1.0 to 2.5 GHz	8	12	–	dB
0.1 dB Loss Compression Input Power ^{Note 1}	P _{in(0.1 dB)}	f = 1.0 GHz	+10	+15	–	dBm
1 dB Loss Compression Input Power ^{Note 2}	P _{in(1 dB)}	f = 1.0 GHz	–	+20	–	dBm
Supply Current	I _{DD}	V _{DD} = V _{cont} = 2.8 V, RF off	–	0.01	1	μA
Switch Control Current	I _{cont}	V _{DD} = V _{cont} = 2.8 V, RF off	–	0.01	1	μA
Switch Control Speed	t _{SW}	f = 1.0 GHz	–	0.4	1	μs

- Notes 1.** P_{in(0.1 dB)} is measured the input power level when the insertion loss increases more 0.1 dB than that of linear range.
- 2.** P_{in(1 dB)} is measured the input power level when the insertion loss increases more 1 dB than that of linear range.

Caution DC blocking capacitors are necessary. Please do not supply any DC bias to the terminals (INPUT1, INPUT2, OUTPUT1, OUTPUT2).

The value of DC blocking capacitors should be chosen to accommodate the frequency of operation, bandwidth, switching speed and the condition with actual board of your system.

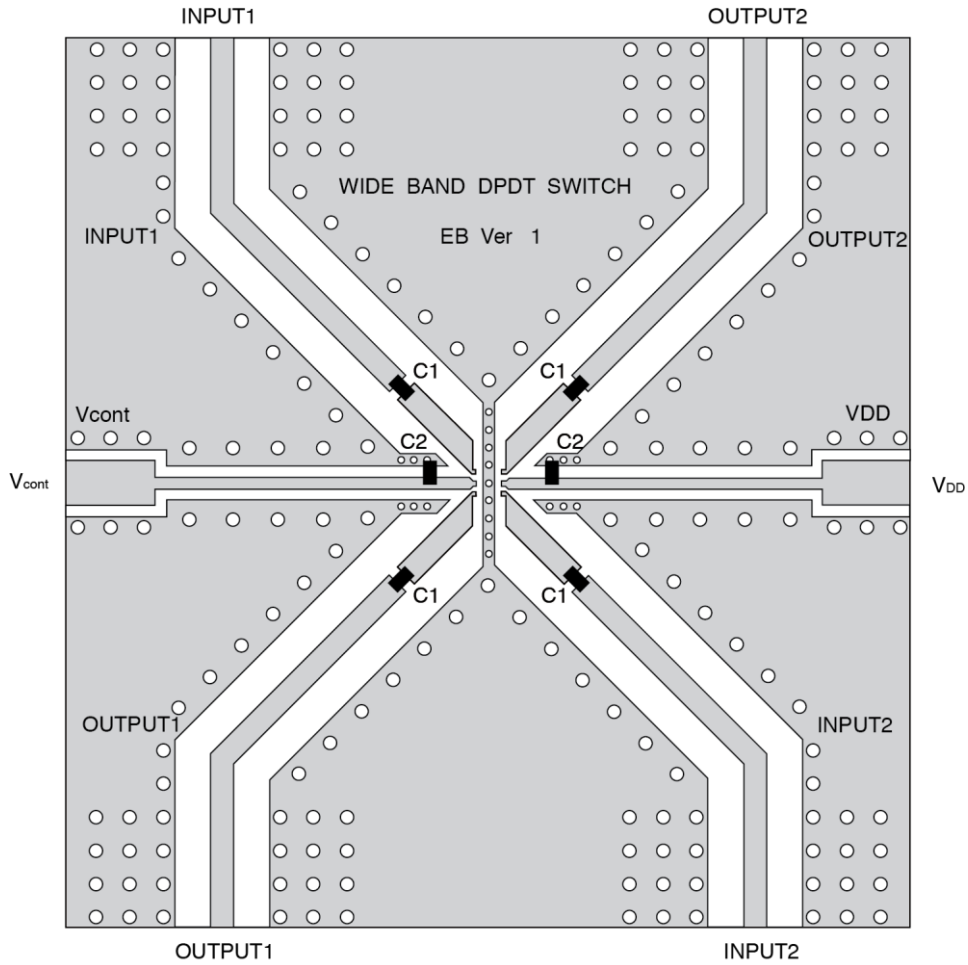
EVALUATION CIRCUIT



Caution This IC has pull down resistances inside between each RF line and GND line, which bias each RF pin internally to GND, then the IC cannot be used for DC switching.

The application circuits and their parameters are for reference only and are not intended for use in actual design-ins.

ILLUSTRATION OF THE TEST CIRCUIT ASSEMBLED ON EVALUATION BOARD

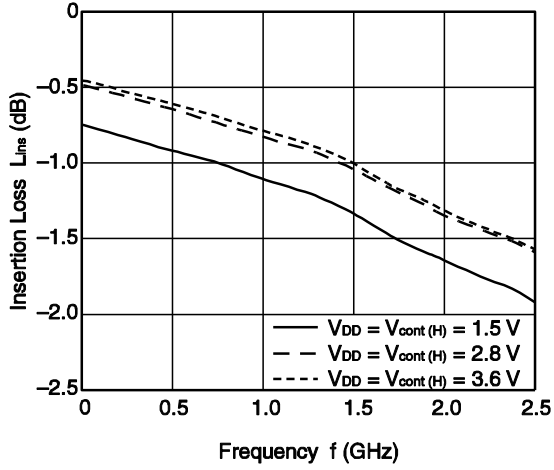


USING THE EVALUATION BOARD

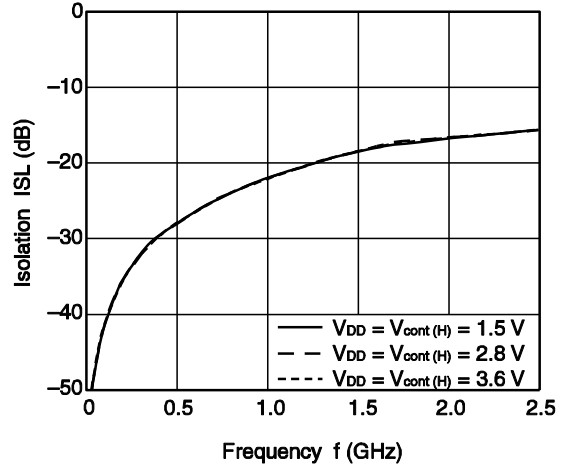
Symbol	Values
C1	1 0000 pF
C2	1 000 pF

TYPICAL CHARACTERISTICS ($T_A = +25^\circ\text{C}$, $V_{DD} = 2.8\text{ V}$, $V_{cont(H)} = 2.8\text{ V}$, $V_{cont(L)} = 0\text{ V}$, $P_{in} = 0\text{ dBm}$, $Z_0 = 50\ \Omega$, DC blocking capacitors = 10 000 pF, unless otherwise specified)

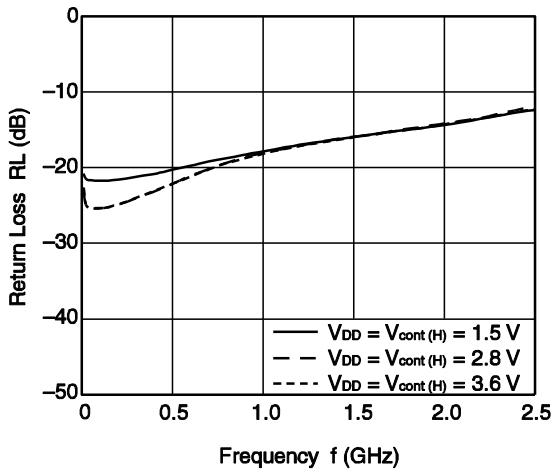
**INPUT1, 2–OUTPUT1, 2
INSERTION LOSS vs. FREQUENCY**



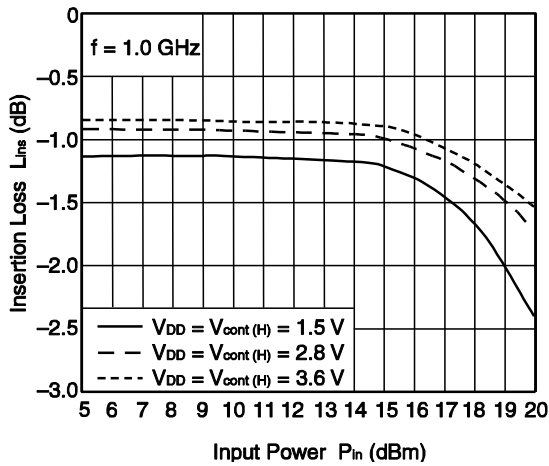
**INPUT1, 2–OUTPUT1, 2
ISOLATION vs. FREQUENCY**



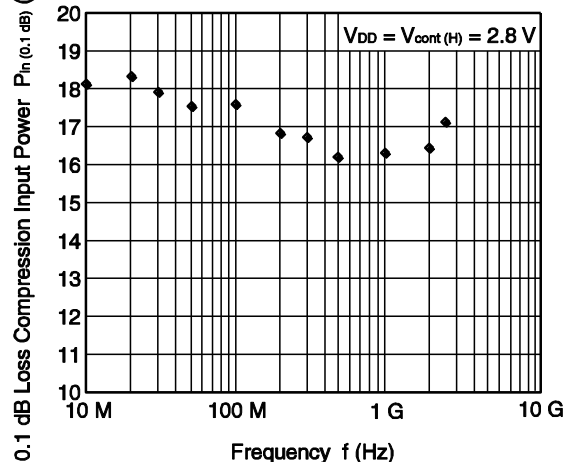
**INPUT1, 2–OUTPUT1, 2
RETURN LOSS vs. FREQUENCY**



INSERTION LOSS vs. INPUT POWER

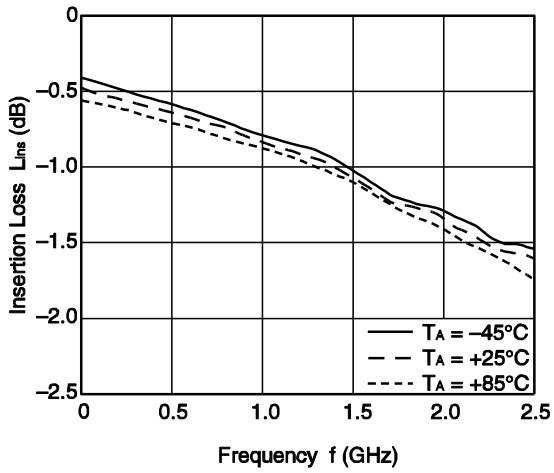


**P_{in} (0.1 dB) vs. FREQUENCY
(for reference)**

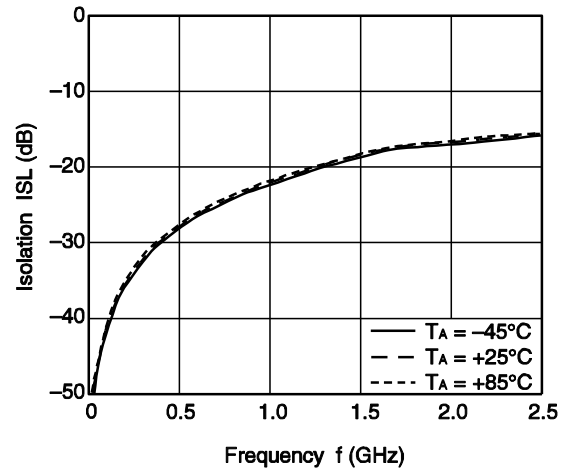


Remark The graphs indicate nominal characteristics.

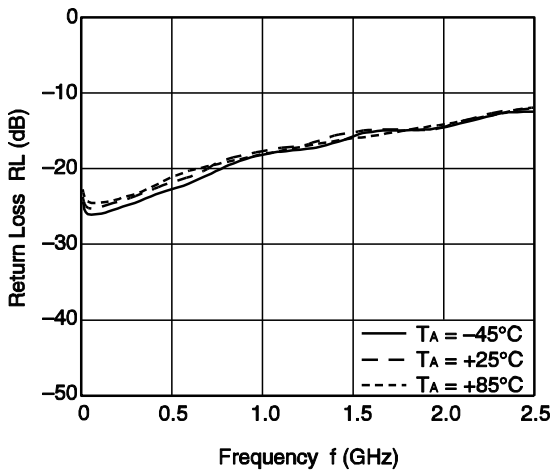
INPUT1, 2-OUTPUT1, 2
INSERTION LOSS vs. FREQUENCY



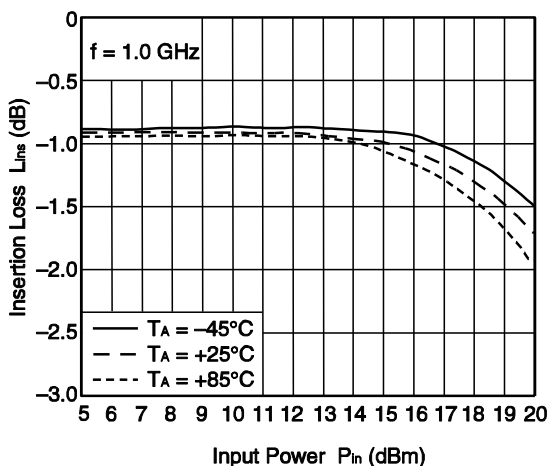
INPUT1, 2-OUTPUT1, 2
ISOLATION vs. FREQUENCY



INPUT1, 2-OUTPUT1, 2
RETURN LOSS vs. FREQUENCY



INSERTION LOSS vs. INPUT POWER

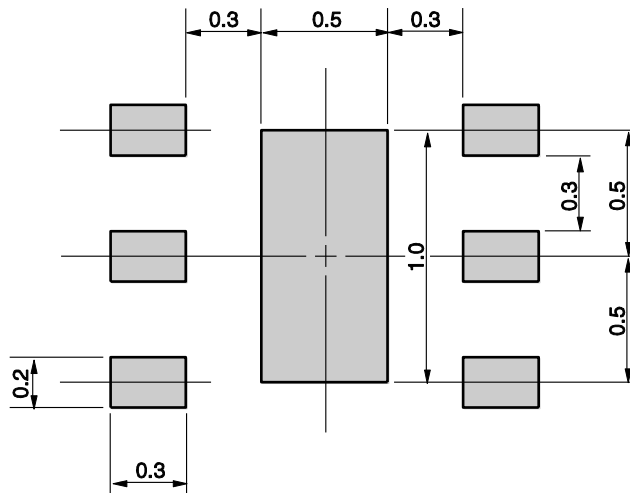


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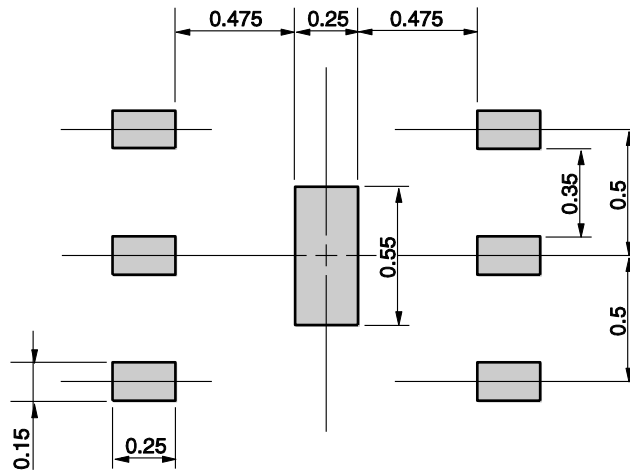
MOUNTING PAD AND SOLDER MASK LAYOUT DIMENSIONS

6-PIN PLASTIC TSON (UNIT: mm)

MOUNTING PAD



SOLDER MASK

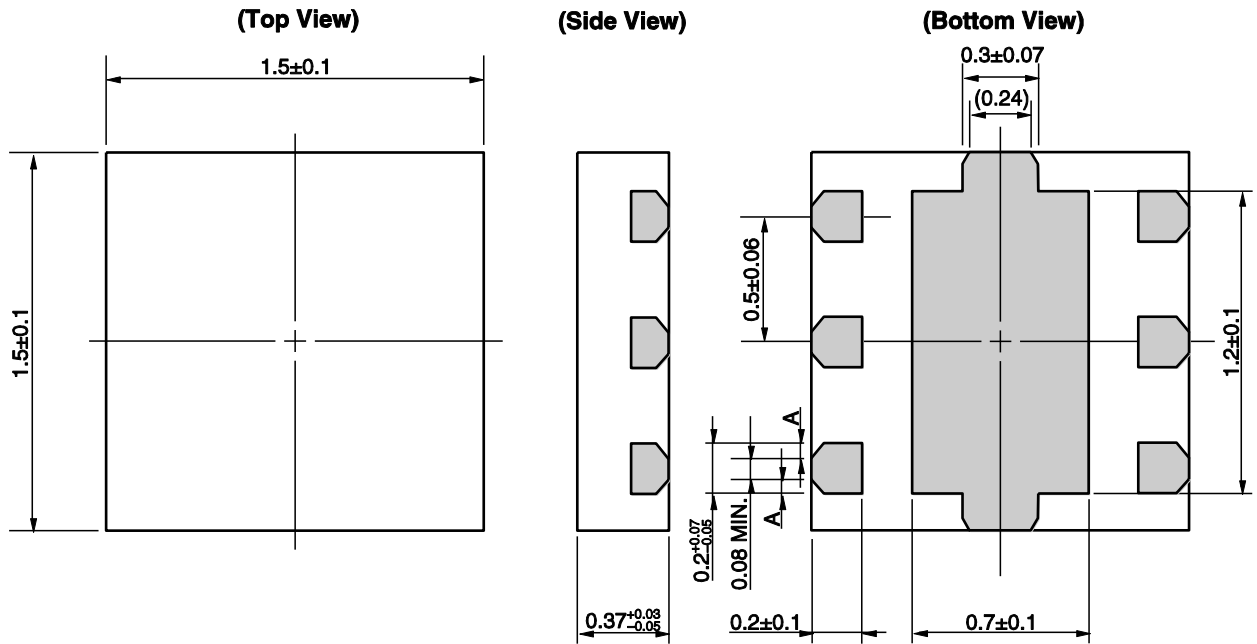


Solder thickness : 0.08 mm

Remark The mounting pad and solder mask layouts in this document are for reference only. When designing PCB, please consider workability of mounting, solder joint reliability, prevention of solder bridge and so on, in order to optimize the design.

PACKAGE DIMENSIONS

6-PIN PLASTIC TSON (T6N) (UNIT: mm)



Remark A>0
 () : Reference value

RECOMMENDED SOLDERING CONDITIONS

This product should be soldered and mounted under the following recommended conditions. For soldering methods and conditions other than those recommended below, contact your nearby sales office.

Soldering Method	Soldering Conditions	Condition Symbol
Infrared Reflow	Peak temperature (package surface temperature) : 260°C or below Time at peak temperature : 10 seconds or less Time at temperature of 220°C or higher : 60 seconds or less Preheating time at 120 to 180°C : 120±30 seconds Maximum number of reflow processes : 3 times Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	IR260
Partial Heating	Peak temperature (terminal temperature) : 350°C or below Soldering time (per side of device) : 3 seconds or less Maximum chlorine content of rosin flux (% mass) : 0.2%(Wt.) or below	HS350

Caution Do not use different soldering methods together (except for partial heating).